No-Residue™ Soldering Flux

IF 2005-series

INTERFLUX® ELECTRONICS

Advantages of Rosin free fluxes (OR)

- Very clean PCB boards
- No contact problems in ICT- test : no delays, no test pin cleaning and damage
- No contact problems on connectors and electrical contacts
- High compatibility with PCB cleaning
- High compatibility with conformal coatings
- Lower maintenance on machine and carrier cleaning
- Cost saving

IF 2005 No-Residue™ flux series

IF 2005M : 1,8%

IF 2005K : 2,5%

IF 2005C : 3,3%

- No-Residue™ Technology
- No-clean
- Alcohol based: activated solvent complex
- OR/L0
- Absolutely rosin and resin free
- Absolutely halogen free
- Used in all electronic branches
- Long history of use worldwide

Application

→ IF 2005 series fluxes are interchangeable.

→ According to the specific case, one type of flux can be more suitable than the other.

Flux	Solid content (%)	LMPA & SnPb Wave soldering	lead-free Wave soldering	Selective Soldering	Component Tinning	Hand Soldering
IF 2005M	1,8	preferred	good	possible	good	possible
IF 2005K	2,5	good	preferred	good	good	possible
IF 2005C	3,3	possible	good	preferred	good	possible

NOTE: *LMPA = low meting point soldering, e.g. with the LMPA-Q alloy*